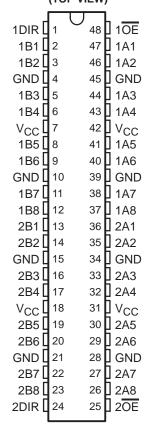
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- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High Drive (-32/64 mA at 3.3-V V_{CC})
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

description

The 'ALVTH16245 devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

SN54ALVTH16245 . . . WD PACKAGE SN74ALVTH16245 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.2 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



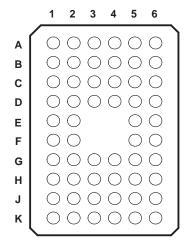
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.



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SN74ALVTH16245 . . . GQL PACKAGE (TOP VIEW)



terminal assignments

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	Vcc	Vcc	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2		_	2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	VCC	VCC	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2OE

NC - No internal connection

ORDERING INFORMATION

T _A PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP – DL	Tape and reel	SN74ALVTH16245DLR	ALVTH16245
400C to 050C	TSSOP – DGG	Tape and reel	SN74ALVTH16245GR	ALVTH16245
-40°C to 85°C	TVSOP – DGV	Tape and reel	SN74ALVTH16245VR	VT245
	VFBGA – GQL	Tape and reel	SN74ALVTH16245QR	
-55°C to 125°C CFP – WD Tub		Tube	SNJ54ALVTH16245WD	SNJ54ALVTH16245WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

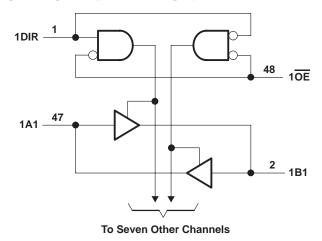
FUNCTION TABLE (each 8-bit section)

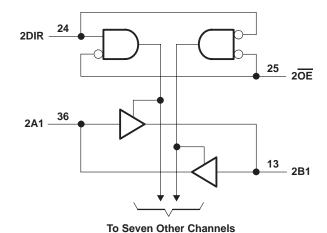
INP	UTS	0050471011			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	X	Isolation			



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logic diagram (positive logic)





Pin numbers shown are for the DGG, DGV, DL, and WD packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}
Input voltage range, V _I (see Note 1)
Voltage range applied to any output in the high or power-off state, V _O (see Note 1)0.5 V to 7 V
Output current in the low state, IO: SN54ALVTH16245
SN74ALVTH16245 128 mA
Output current in the high state, I _O : SN54ALVTH16245 –48 mA
SN74ALVTH16245 –64 mA
Input clamp current, I_{IK} ($V_I < 0$)
Output clamp current, I_{OK} ($V_O < 0$)
Package thermal impedance, θ _{JA} (see Note 2): DGG package
DGV package 58°C/W
DL package 63°C/W
GQL package 42°C/W
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions, $V_{\mbox{CC}}$ = 2.5 V \pm 0.2 V (see Note 3)

			SN54	ALVTH1	6245	SN74	ALVTH1	6245	
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage		2.3		2.7	2.3		2.7	V
VIH	High-level input voltage		1.7		7	1.7			V
V _{IL}	Low-level input voltage			Š	0.7			0.7	V
VI	Input voltage		0	V _C C	5.5	0	VCC	5.5	V
loн	High-level output current			1	-6			-8	mA
	Low-level output current			2	6			8	4
lor	Low-level output current; current duty cycle ≤ 5	50%; f≥1 kHz	Š	5	18			24	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54	SN54ALVTH16245			SN74ALVTH16245		
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Vcc	Supply voltage		3		3.6	3		3.6	V
VIH	High-level input voltage		2		7	2			V
V _{IL}	Low-level input voltage			Š	0.8			8.0	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
IOH	High-level output current			7	-24			-32	mA
	Low-level output current			2	24			32	A
loL	Low-level output current; current duty cycle ≤	50%; f ≥ 1 kHz	Š	5	48			64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔVCC	Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature	_	-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

				SN54	ALVTH1	6245	SN74	ALVTH1	6245	LINUT	
PA	ARAMETER	TEST CO	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT	
٧ıK		$V_{CC} = 2.3 \text{ V},$	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2			
∨он		V 22V	$I_{OH} = -6 \text{ mA}$	1.8						V	
		V _{CC} = 2.3 V	$I_{OH} = -8 \text{ mA}$				1.8				
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OL} = 100 μA			0.2			0.2		
			$I_{OL} = 6 \text{ mA}$			0.4					
VOL		V 22V	$I_{OL} = 8 \text{ mA}$						0.4	V	
		V _{CC} = 2.3 V	I _{OL} = 18 mA			0.5					
			$I_{OL} = 24 \text{ mA}$			4			0.5		
	Control inputs	$V_{CC} = 2.7 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 2.7 \text{ V},$	V _I = 5.5 V		4	10			10		
Ц			V _I = 5.5 V		N.	20			20	μΑ	
	A or B ports	V _{CC} = 2.7 V	VI = VCC		S	1			1		
			V _I = 0		5	-5			-5		
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	Q	Y				±100	μΑ	
I _{BHL} ‡		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ	
IBHH§		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V		-10			-10		μΑ	
IBHLO		$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ	
Івнно)#	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ	
IEX		$V_{CC} = 2.3 \text{ V},$	$V_0 = 5.5 \text{ V}$			125			125	μΑ	
IOZ(PL	J/PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \frac{0.5}{\text{OE}} \text{ V}$ V _I = GND or V _{CC} , $\overline{\text{OE}}$ =	to V _{CC} , don't care			±100			±100	μΑ	
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1		
ICC		$I_{O} = 0$,	Outputs low		2.3	4.5		2.3	4.5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1		
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0		3.5			3.5		pF	
C _{io}		$V_{CC} = 2.5 \text{ V},$	V _O = 2.5 V or 0		8			8		pF	

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

[¶] An external driver must source at least I_{BHLO} to switch this node from low to high.

[#] An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54ALVTH16245		6245	SN74ALVTH16245			UNIT	
PAR	RAMETER	TEST C	ONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
VIK		V _{CC} = 3 V,	I _I = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	VCC-0	.2		V _{CC} -0.	.2			
∨он		V 2 V	$I_{OH} = -24 \text{ mA}$	2						V	
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2				
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	$I_{OL} = 100 \mu A$			0.2			0.2		
			$I_{OL} = 16 \text{ mA}$						0.4		
		V _{CC} = 3 V	$I_{OL} = 24 \text{ mA}$			0.5				V	
VOL			$I_{OL} = 32 \text{ mA}$						0.5	V	
			$I_{OL} = 48 \text{ mA}$			0.55					
			$I_{OL} = 64 \text{ mA}$			4			0.55		
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND		3	±1			±1		
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		W. W.	10			10		
lį			V _I = 5.5 V		7	20			20	μА	
	A or B ports		$V_I = V_{CC}$		2	1			1		
			V _I = 0		5	-5			-5		
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	Q					±100	μΑ	
I _{BHL} ‡		$V_{CC} = 3 V$,	V _I = 0.8 V	75			75			μΑ	
I _{BHH} §		$V_{CC} = 3 V$,	V _I = 2 V	-75			-75			μΑ	
IBHLO¶		$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ	
^І внно [#]	#	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ	
{IEX}		$V{CC} = 3 V$,	$V_0 = 5.5 \text{ V}$			125			125	μΑ	
IOZ(PU/	/PD) [☆]	$V_{CC} \le 1.2 \text{ V}, V_{O} = \underline{0.5} \text{ V}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}} = \underline{0.5} \text{ V}$	V to V _{CC} , = don't care			±100			±100	μА	
		V _{CC} = 3.6 V,	Outputs high		0.07	0.1		0.07	0.1		
ICC		$I_{O} = 0$,	Outputs low		3.2	5		3.2	5	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		0.07	0.1		0.07	0.1		
∆lcc□		V _{CC} = 3 V to 3.6 V, One Other inputs at V _{CC} or			_	0.2		_	0.2	mA	
Ci		V _{CC} = 3.3 V,	V _I = 3.3 V or 0		3.5			3.5		pF	
C _{io}		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		8			8		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[¶] An external driver must source at least I_{BHLO} to switch this node from low to high.

[#]An external driver must sink at least IBHHO to switch this node from high to low.

Current into an output in the high state when VO > VCC

^{*}High-impedance state during power up or power down

 $[\]Box$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

24244555	FROM	то	SN54ALVTH16245		SN74AL\		
PARAMETER	(INPUT)	(OUTPUT)		MAX	MIN	MAX	UNIT
^t PLH	A on D	B or A	0.5	3.6	0.5	3.6	
t _{PHL}	A or B		0.5	3.4	0.5	3.4	ns
^t PZH	ŌĒ	A D	1.5	4.9	1.5	4.9	
t _{PZL}	OE .	A or B	1.5	4	1	4	ns
^t PHZ	ŌĒ	A or P	1.5	4.9	1.5	4.9	20
t _{PLZ}	OE OE	A or B	29	4.2	1	4.2	ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	SN54ALVTH16245		SN74AL\		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	UNIT
^t PLH	A - :: B	D. v. A	0.5	3.1	0.5	3.1	
^t PHL	A or B	B or A	0.5	2.9	0.5	2.9	ns
^t PZH	OE	A D	1	4.2	1	4.2	
tPZL	OE OE	A or B	1.9	3.5	1	3.5	ns
^t PHZ	- ŌĒ	A or D	1.5	5.3	1.5	5.3	
t _{PLZ}		A or B	1.5	5	1.5	5	ns

skew

 t_{ps} (pin or transition skew), $t_{ps} = |t_{PHL} - t_{PHL}|$

ps , p.			
	V _{CC} = 2.5 V	V _{CC} = 3.3 V	LINUT
	TYP	TYP	UNIT
t _{ps} max	438	118	ps

t_{OST} = $|t_{p\Phi m} - t_{p\Phi n}|$, where Φ is any edge transition (high to low or low to high) measured between any two outputs (m or n) within any given device (see Note 4)

		$V_{CC} = 2.5 V$	$V_{CC} = 3.3 V$	LINUT
		TYP	TYP	UNIT
4	A–B	227	248	
tost	B–A	223	243	ps

NOTE 4: One output switching, $T_A = 25^{\circ}C$

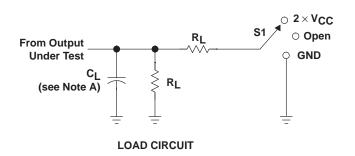
t_{OSHL}/t_{OSLH} (common edge skew), $t_{OSHL} = |t_{PHL} max - t_{PHL} min|$ (output skew for low-to-high transitions), and $t_{OSLH} = |t_{PLH} max - t_{PLH} min|$ (output skew for high-to-low transitions) (see Note 4)

		$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$				
		TYP	TYP	UNIT			
^t OSLH		210	145	ps			
^t OSHL	A–B	243	351				
^t OSLH	B-A	207	136	20			
^t OSHL	D-A	238	350	ps			

NOTE 4: One output switching, $T_A = 25^{\circ}C$

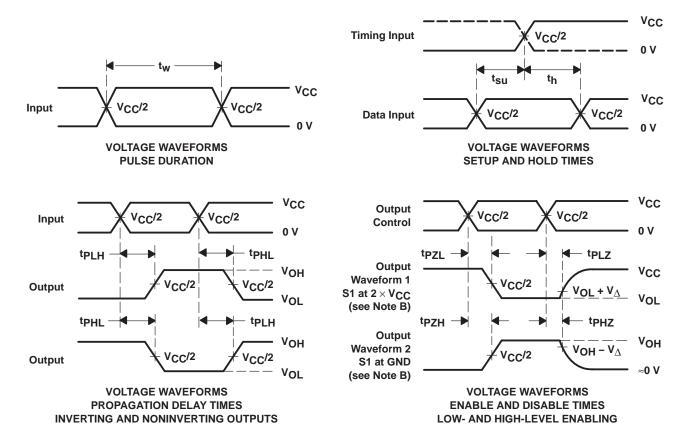


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	2×V _{CC}
tPHZ/tPZH	GND

VCC	CL	RL	$v_{\scriptscriptstyle\Delta}$	
2.5 V ±0.2 V	30 pF	500 Ω	0.15 V	
3.3 V ±0.3 V	50 pF	500 Ω	0.3 V	



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Ī	Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
							(4)	(5)		
ſ	SN74ALVTH16245VR	Obsolete	Production	TVSOP (DGV) 48	-	-	Call TI	Call TI	-40 to 85	VT245

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



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